

STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Canceled)**
2. **(Currently Amended)** An apparatus according to claim ~~421~~, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.
3. **(Currently Amended)** An apparatus according to claim 2, wherein said brush roller comprises an electrically conductive material.
4. **(Currently Amended)** An apparatus according to claim 3, wherein said brush roller comprises a polymer filled with an electrically-conductive material.
5. **(Currently Amended)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.
6. **(Currently Amended)** An apparatus according to claim ~~421~~, wherein said rotating wafer-cleaning member is part of said electrically-conductive path.
7. **(Currently Amended)** An apparatus according to claim ~~63~~, wherein said ~~cleaning member~~ is a rotational brush roller comprises a foam rubber cleaning portion.
8. **(Withdrawn and Currently Amended)** An apparatus according to claim ~~421~~, wherein said ~~electrically-conductive electrical~~ grounding path includes at least one contact that engages the ~~article~~ microelectronics wafer at a location spaced from said rotating wafer-cleaning member during at least a portion of the time said rotating wafer-cleaning member is engaged with the ~~article~~ microelectronics wafer.
9. **(Withdrawn and Currently Amended)** An apparatus according to claim 8, wherein said rotating wafer-cleaning member has a leading side and a trailing side and said at least one contact is located proximate one of said leading side and said trailing side.

10. **(Currently Amended)** A method of removing surface contaminants from a surface of an ~~article~~ a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:
- (a) providing a microelectronics wafer having a surface;
 - (b) cleaning the said surface of the article said microelectronics wafer with a rotating wafer-cleaning member so as to remove at least some of the surface contaminants; and
 - (b) during at least part of the time that step (a) is being performed, contacting the article said microelectronics wafer with a conductive member connected to so as to create an electrical ground path between said surface and an electrical ground.
11. **(Currently Amended)** A method according to claim 10, wherein said rotating wafer-cleaning member is electrically conductive and step (b) includes contacting said rotating wafer-cleaning member with ~~the article~~ said microelectronics wafer.
12. **(Currently Amended)** A method according to claim 10, wherein step (a) includes contacting ~~the said surface~~ with said rotating wafer-cleaning member.
13. **(Currently Amended)** A method according to claim 12, wherein step (a) includes brushing ~~the said surface~~ with said rotating wafer-cleaning member.
14. **(Currently Amended)** A method according to claim 13, wherein step (a) includes ~~rotating said cleaning member at least during the time said cleaning member is in contact with the surface~~ contacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.
15. **(Withdrawn and Currently Amended)** A method according to claim 10, wherein step (b) includes contacting ~~the article~~ said microelectronics wafer with at least one contact spaced from said rotating wafer-cleaning member.
16. **(Withdrawn)** A method according to claim 15, wherein step (b) includes contacting said at least one contact with said surface.

17. **(Currently Amended)** A system for removing surface contaminants from a surface, comprising:
- (a) ~~an electronic article~~ a microelectronics wafer ~~and~~ having a surface;
 - (b) a wafer-cleaning region receiving said microelectronics wafer;
 - (~~b~~c) a rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface;
 - (~~e~~d) an electrical ground; and
 - (~~e~~) an electrically-conductive path extending from said ~~article~~ microelectronics wafer to said ground.
18. **(Currently Amended)** A system according to claim 17, wherein said rotating wafer-cleaning member comprises a ~~rotational brush~~ roller having a non-filamentous cleaning surface.
19. **(Currently Amended)** A system according to claim 18, wherein said ~~rotational brush~~ roller is part of said electrically-conductive path.
20. **(Withdrawn and Currently Amended)** A system according to claim 17, wherein said electrically-conductive path includes at least one contact that engages said ~~electronic article~~ microelectronics wafer at a location spaced from said rotating wafer-cleaning member during at least a portion of the time said cleaning member is engaged with said ~~electronic article~~ microelectronics wafer.
21. **(New)** An apparatus for cleaning surface contaminants from a microelectronics wafer, comprising:
- (a) a wafer cleaning region configured to receive a microelectronics wafer during cleaning;
 - (b) a rotating wafer-cleaning member designed to contact the microelectronics wafer during cleaning so as to remove surface contaminants from the microelectronics wafer during cleaning; and
 - (c) an electrical grounding path extending from the microelectronic wafer to an electrical ground when the apparatus is connected to the electrical ground.